LNJ912W8CRA1

Hight Bright Surface Mounting Chip LED

TSS Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit					
Power dissipation	P _D	65	mW					
Forward current	$I_{\rm F}$	15	mA					
Pulse forward current *	I _{FP}	55	mA					
Reverse voltage	V _R	5	V					
Operating ambient temperature	T _{opr}	-30 to +85	°C					
Storage temperature	T _{stg}	-40 to +100	°C					
Note) *: The condition of I _{FP} is duty 10%, Pulse width 1 msec.								

Lighting Color

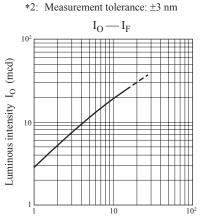
• Blue

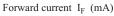
		atoriation 7	acocu 200
Electro-O	ptical Chara		$l_a = 25^{\circ}C \pm 3^{\circ}C$

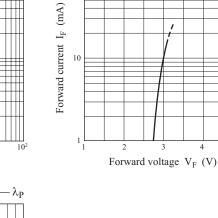
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I _O	$I_F = 5 \text{ mA}$	5.0	12.0	41.8	mcd
Reverse current	I _R	$V_R = 5 V$			100	μΑ
Forward voltage	V _F	$I_F = 5 \text{ mA}$		2.90	3.20	V
Peak emission wavelength	λ_{P}	$I_F = 5 \text{ mA}$		465		nm
Dominant emission wavelength *2	λ_d	$I_F = 5 \text{ mA}$	462	470	478	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		20		nm

 I_F $-V_F$

Note) *1: Measurement tolerance: ±20%

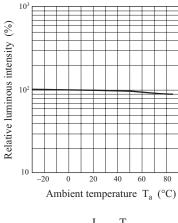






 10^{2}

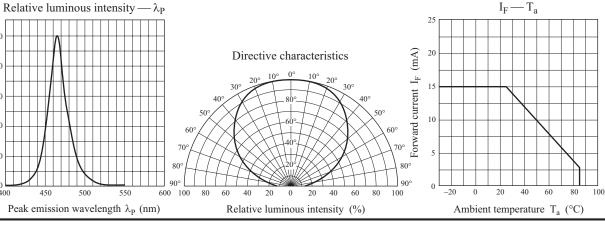
10



Relative luminous intensity

-Ta

100



5

Publication date: November 2011

Relative luminous intensity (%)

80

60

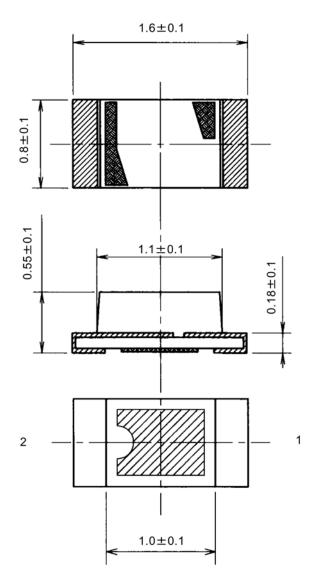
40

20

0 L 400

Package (Unit: mm)

KLTFTN2K1200



• Pin name

1: Anode

2: Cathode

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